瀚荃股份有限公司
CviLux Corporation

CVILUX
2020.04.16
ISSUED

ENGINEERING DEPT.		PRODUCT SPECIFICATION For 2.00 mm (.079″) Board to Board Connectors of System CB74	SPEC.NO.: SPCB016C
REVISIONS	ECNT120076		PAGE: 1/5

1. SCOPE:
This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: **CB74 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

0.8 mm (.031″) ~ 1.6 mm (.063″)

REVIEWED : Eisley APPROVED : Eisley VERIFIED : Michelle .

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute form housing	More than 400 gram
8.2	Single contact insertion force	Measure force to insertion using 0.46 mm square pin at speed 25± 3 mm per minute	600 gram max.
8.3	Single contact withdrawal force	Measure force to withdrawal using 0.46 mm square pin at speed 25± 3 mm per minute	20 gram min.
8.4	Durability	Connector shall be subjected to 50 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solderability	**Tin-Lead Process:** Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C **Lead-Free Process:** Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area

	ITEM	TEST CONDITION	REQUIREMENT
9.3	Resistance to soldering heat	**DIP Type Tin-Lead Process:** Soldering time: 5 ± 0.5 second Soldering pot: 240 ± 5°C **DIP Type Lead-Free Process** Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5°C **SMT Tin-Lead Type Process:** Refer Reflow temperature profile(11.1) Soldering time: 10 second Max. Soldering pot: 230 ± 5 °C **SMT Type Lead-Free Process:** Soldering time: 20 second Max. Soldering pot: 250~260°C Refer Reflow temperature profile(11.2)	No damage
9.4	Heat aging	105± 2°C, 96 hours	No damage
9.5	Humidity	40±2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.6	Temperature cycling	One cycle consists of : (1) -55^{+0}_{-3} °C , 30 min. (2)Room temp. 10-15 min. (3) 85^{+3}_{-0} °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial

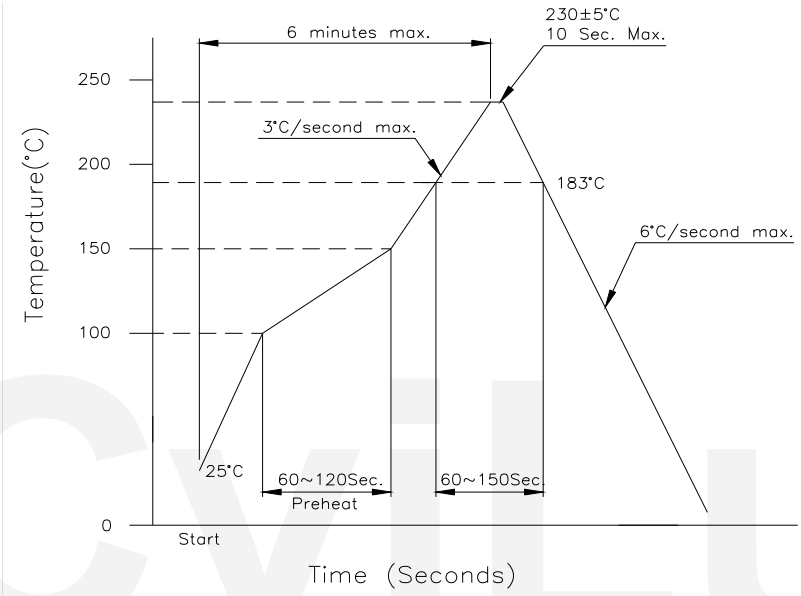
	ITEM	TEST CONDITION	REQUIREMENT
9.7	Salt spray	Temperature: 35 ± 3°C Solution: 5 ± 1% Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE:

-40 to + 105°C ; + 215°C intermittent (Vapor Phase Solder Reflow) for SMT type

11. Recommended IR Reflow Temperature Profile:

11.1 Using Typical Solder Paste



11.2 Using Lead-Free Solder Paste